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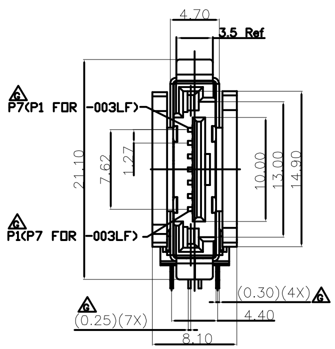
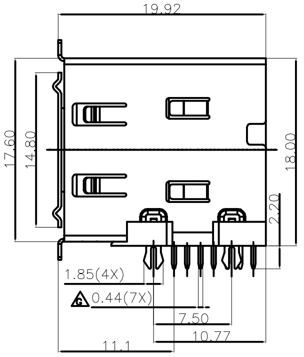
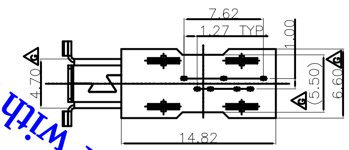
PRODUCT NO.
10074141−001LF
10074141−003LF

G







NOTES:

1.MATERIAL:
HOUSING:THERMALPLASTIC HIGH TEMP WITH 30% G/F UL94 V−0
COLOR:BLACK
CONTACT:COPPER ALLOY
SHELL/BOARD LOCK: COPPER ALLOY

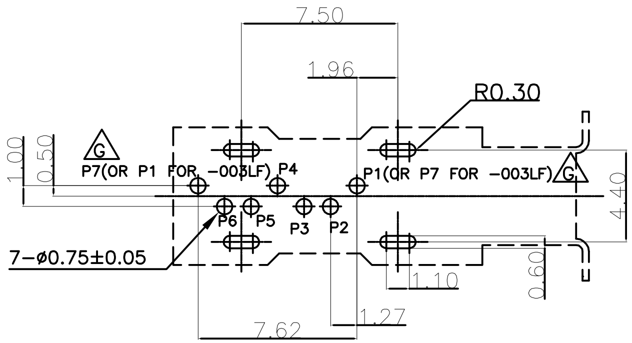
2.FINISH:
CONTACT:GOLD PLATING ON CONTACT AREA
100u" MIN. MATT TIN PLATING ON SOLDERTAILS
50u" MIN.NICKEL UNDERPLATING OVER ALL
SHELL/BOARD LOCK:50 u" MIN.NICKEL PLATING OVER ALL

3. THE HOUSING WILL WITHSTAND TO 260C FOR 10 SEC IN A WAVE SOLDER APPLICATION WITH A 1.6MM PCB

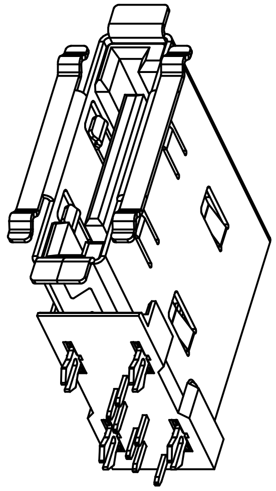
4. PRODUCT SPEC : GS−12−386
PACKING SPEC : GS−14−1109

5. PRODUCT NUMBERING:
10074141 −0 0 X X LF —— LEAD FREE
PACKING:
BLANK: TRAY PACKING
1: 15u" GOLD PLATING
2: G/F GOLD PLATING
3: 15u" GOLD PLATING WITH NEW PINOUT ASSIGNMENT G
0: LAYOUT#1

6. A SYMBOL G WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION



RECOMMEND P.C.BOARD LAYOUT
PCB TOLERANCE:±0.05



PIN DEFINITON

ESATA	
NAME	TYPE
P1	GND
P2	A+
P3	A−
P4	GND
P5	B−
P6	B+
P7	GND

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mat'l. code				surface		tolerance		projection	product family		
14				ISO 1302	58	ISO 406	ISO 1101		533		
ltr	ecn no	dr	date	tolerances unless otherwise specified					title		
A	T07−1074	S.LIN	2007−05−23	angles	linear	.X±0.38		MM	E−SATA_UP_RIGHT DIP_TYPE		
B	T08−1082	S.LIN	2008−04−29			.XX±0.25					
C	T10−0184	S.LIN	2010−12−14	0°±2°		.XXX±0.100		scale 2:1			
D	T−00544	OS.LIN	2011−08−31	dr	STERLING.LIN	2007−05−21		Amphenol FCi	dwg no	sheet 1 of 3	size
E	ELX−S−007081	HKL	2011−10−17	engr	HKLIM	2016−03−03			10074141		A3
F	ELX−S−011879	HKL	2012−06−08	chr	HKLIM	2016−03−03					
G	ELX−S−23409	HKL	2016−03−03	appd	KPTAY	2016−03−03			type	PRODUCT−CUSTOMER_DRW	Drawing

sheet index	revision	G	G	G	107	109	111	113	115	117	119	121	123	125	127	129	131	133	135	137	139
	sheet	1	2	3	106	108	110	112	114	116	118	120	122	124	126	128	130	132	134	136	138

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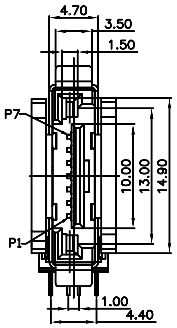
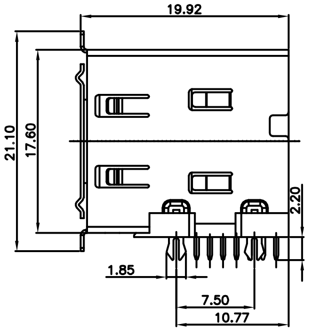
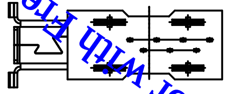




NOTES:
1.MATERIAL:
HOUSING:THERMALPLASTIC HIGH TEMP WITH 30% G/F UL94 V-0
COLOR:BLACK
CONTACT:COPPER ALLOY
SHELL/BOARD LOCK: COPPER ALLOY
2.FINISH:
CONTACT:GOLD PLATING ON CONTACT AREA
100u" MIN. MATT TIN PLATING ON SOLDERTAILS
50u" MIN.NICKEL UNDERPLATING OVER ALL
BOARD LOCK:50u" MIN.NICKEL PLATING OVER ALL
80u" MIN.MATT TIN PLATING OVER ALL
SHELL/BOARD LOCK:50u" MIN.NICKEL PLATING OVER ALL
3. THE HOUSING WILL WITHSTAND TO 260C FOR 10 SEC
IN A WAVE SOLDER APPLICATION WITH A 1.6MM PCB

4. PRODUCT SPEC : GS-12-386
PACKING SPEC : GS-14-1109
5. PRODUCT NUMBERING:
10074141 -1 0 X X LF —— LEAD FREE
PACKING:
BLANK: TRAY PACKING
1: 15u" GOLD PLATING
2: G/F GOLD PLATING
1: LAYOUT#2
6. A SYMBOL ⚠G WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE, WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION



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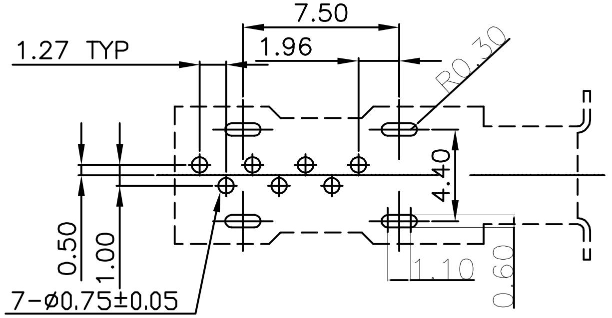
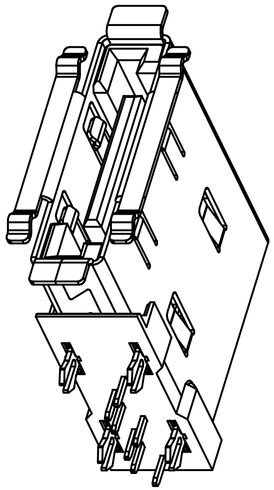


P.C.BOARD MOUNTING DIMENSIONS T=1.60mm

PCB TOLERANCE: ±0.05



PIN DEFINITON

ESATA	
NAME	TYPE
P1	GND
P2	A+
P3	A−
P4	GND
P5	B−
P6	B+
P7	GND

mat'l. code 14

surface 58 ISO 1302

tolerance ISO 406 ISO 1101

projection

product family 533

title E-SATA_UP_RIGHT DIP_TYPE

ltr	ecn no	dr	date
A	T07-1074	S.LIN	2007-05-23
B	T08-1082	S.LIN	2008-04-29
C	T10-0184	S.LIN	2010-12-14
D	T-005440	S.LIN	2011-08-31
E	ELX-S-007081	HKL	2011-10-17
F	ELX-S-011879	HKL	2012-06-08
G	ELX-S-23409	HKL	2016-03-03

tolerances unless otherwise specified

angles	linear	.X±0.38
		.XX±0.25
0°±2°		.XXX±0.100

MM

scale 2:1

dr	STERLING.LIN	2007-05-21
engr	HKLIM	2016-03-03
chr	HKLIM	2016-03-03
appd	KPTAY	2016-03-03

dwg no 10074141

sheet 2 of 3

size A3

type PRODUCT-CUSTOMER_DRW Drawing

sheet index																				
revision	G	G	G	107	109	111	113	115	117	119	121	123	125	127	129	131	133	135	137	139
sheet	1	2	3	106	108	110	112	114	116	118	120	122	124	126	128	130	132	134	136	138

form: A3-2016-02-24

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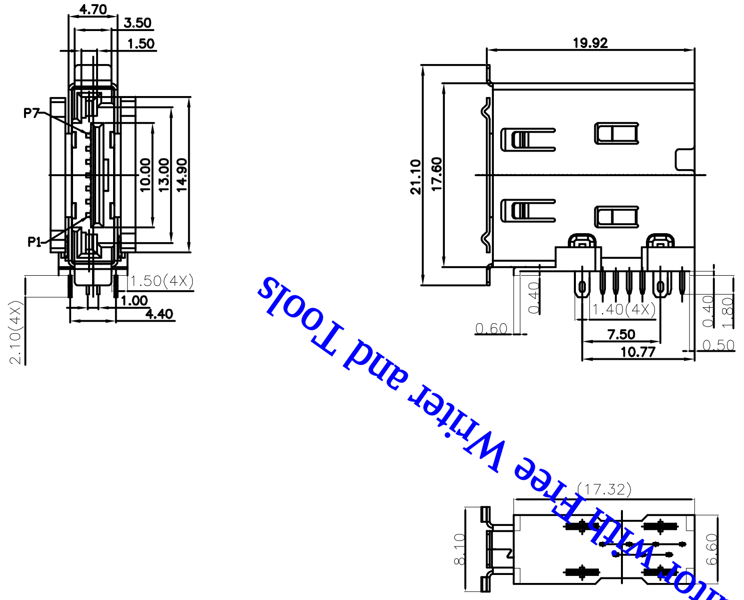

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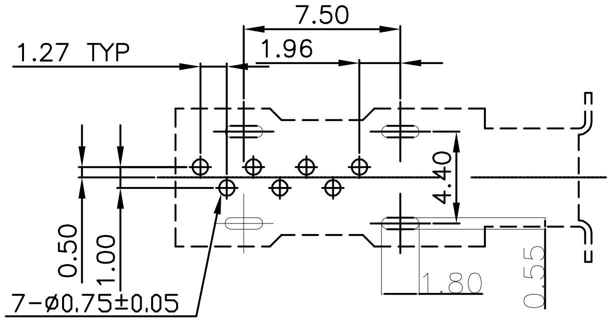
NOTES:
1.MATERIAL:
HOUSING: THERMOPLASTIC HIGH TEMP WITH 30% G/F UL94 V-0
COLOR:BLACK
CONTACT: COPPER ALLOY
SHELL/BOARD LOCK: COPPER ALLOY
2.FINISH:
CONTACT:GOLD PLATING ON CONTACT AREA
120u" MIN. MATT TIN PLATING ON SOLDERTAILS
50u" MIN.NICKEL UNDERPLATING OVER ALL
BOARD LOCK: 50u" MIN.NICKEL PLATING OVER ALL
120u" MIN.MATT TIN PLATING OVER ALL
SHELL/BOARD LOCK: 50u" MIN.NICKEL PLATING OVER ALL
3. THE HOUSING WILL WITHSTAND TO 260C FOR 10 SEC
IN A WAVE SOLDER APPLICATION WITH A 1.6MM PCB
4. PRODUCT SPEC : GS-12-386
PACKING SPEC : GS-14-1109
5. PRODUCT NUMBERING:
10074141 -2 0 X X LF —— LEAD FREE
PACKING:
BLANK: TRAY PACKING
1: 15u" GOLD PLATING
2: G/F GOLD PLATING
2: LAYOUT#3
6. A SYMBOL ⚠G WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE, WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION



P.C.BOARD MOUNTING DIMENSIONS T=1.60mm
PCB TOLERANCE: ±0.05

PIN DEFINITON

ESATA	
NAME	TYPE
P1	GND
P2	A+
P3	A−
P4	GND
P5	B−
P6	B+
P7	GND

mat'l. code 14
surface 58 ✓ ISO 1302
tolerance ISO 406 ISO 1101
projection
product family 533

ltr	ecn no	dr	date
A	T07−1074	S.LIN	2007−05−23
B	T08−1082	S.LIN	2008−04−29
C	T10−0184	S.LIN	2010−12−14
D	T−005440	S.LIN	2011−08−31
E	ELX−S−007081	HKL	2011−10−17
F	ELX−S−011879	HKL	2012−06−08
G	ELX−S−23409	HKL	2016−03−03

tolerances unless otherwise specified
angles 0°±2°
linear .X±0.38 .XX±0.25 .XXX±0.100
MM
scale 2:1

dr	STERLING.LIN	2007−05−21
engr	HKLIM	2016−03−03
chr	HKLIM	2016−03−03
appd	KPTAY	2016−03−03

Amphenol FCi

title
E−SATA_UP_RIGHT
DIP_TYPE

dwg no 10074141
sheet 3 of 3
size A3
type PRODUCT−CUSTOMER_DRW Drawing

sheet index																				
revision	1	2	3	107	109	111	113	115	117	119	121	123	125	127	129	131	133	135	137	139
sheet	G	G	G	106	108	110	112	114	116	118	120	122	124	126	128	130	132	134	136	138

form: A3-2016-02-24